

II. Listing of the Claims

1. (Currently Amended) An assembly having an axis and comprising:

a housing having an inner wall and defining an axis,

a first support perpendicular to the axis and having a first support perimeter,

a first microelectronic module affixed to the first support,

a second support perpendicular to the axis and having a second support perimeter;

a second microelectronic module affixed to the second support; and

a plurality of ribs, each rib being attached to the first support at the first support perimeter outboard the first microelectronic module and to the second support at the second support perimeter outboard the second microelectronic module and extending axially therebetween to maintain said first support and said second support in parallel, spaced relationship,

the ribs engaging the inner wall of the housing and spacing the first and second microelectronic modules and the first and second supports apart from the inner wall when the microelectronic assembly is coaxially received in the housing.

2. (Original) The assembly of claim 1 further comprising a connector strip connected to the first microelectronic module and to the second microelectronic module and extending axially for connecting said first microelectronic module and said second microelectronic module to an external circuit.

3. (Original) The assembly of claim 1 wherein the first support perimeter and the second support perimeter are substantially coextensive.

4. (Currently Amended) The assembly of claim 1 wherein the first support perimeter comprises a first attachment tab projecting outwardly therefrom, and wherein the second support perimeter comprises a second attachment tab projecting outwardly therefrom, and wherein the assembly includes a rib of the plurality of ribs attached to the first attachment tab and the second attachment tab.

5. (Original) The assembly of claim 1 wherein the first microelectronic module comprises a flexible substrate and a plurality of electronic components attached to the flexible substrate.

6. (Original) The assembly of claim 5 wherein the second microelectronic module comprises a flexible substrate and a plurality of electronic components attached to the flexible substrate.

7. (Currently Amended) The assembly of claim 1 wherein the first microelectronic module is generally circular and includes a chordal edge, and wherein the assembly further comprises a connector strip connected to the first microelectronic module adjacent at said chordal edge.

8. (Cancelled)

9. (Currently Amended) The assembly of claim 8 1 wherein the spacing between the inner wall and the first and second microelectronic assemblies is adapted for cooling gas flow.